

| PCN Number: | 20210903001.1 | | PCN Date: | September 27, 2021 | | | | | | |
|--|--|---|---|--------------------------|---------------------|-----------------|-------------|---------------|---------|---------|
| Title: | Qualification of CDAT as an alternate Assembly site for Select Devices | | | | | | | | | |
| Customer Contact: | PCN Manager | Dept: | Quality Services | | | | | | | |
| Proposed 1st Ship Date: | Dec 27, 2021 | Estimated Sample Availability: | Date provided at sample request | | | | | | | |
| Change Type: | | | | | | | | | | |
| <input checked="" type="checkbox"/> | Assembly Site | <input type="checkbox"/> | Design | <input type="checkbox"/> | Wafer Bump Site | | | | | |
| <input type="checkbox"/> | Assembly Process | <input type="checkbox"/> | Data Sheet | <input type="checkbox"/> | Wafer Bump Material | | | | | |
| <input checked="" type="checkbox"/> | Assembly Materials | <input type="checkbox"/> | Part number change | <input type="checkbox"/> | Wafer Bump Process | | | | | |
| <input type="checkbox"/> | Mechanical Specification | <input type="checkbox"/> | Test Site | <input type="checkbox"/> | Wafer Fab Site | | | | | |
| <input type="checkbox"/> | Packing/Shipping/Labeling | <input type="checkbox"/> | Test Process | <input type="checkbox"/> | Wafer Fab Materials | | | | | |
| | | | | <input type="checkbox"/> | Wafer Fab Process | | | | | |
| PCN Details | | | | | | | | | | |
| Description of Change: | | | | | | | | | | |
| <p>Texas Instruments Incorporated is announcing the qualification of CDAT as an additional Assembly site for the list of devices shown below. Construction differences between the 2 sites are as follows:</p> <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th></th> <th style="text-align: center;">TI Clark</th> <th style="text-align: center;">CDAT</th> </tr> </thead> <tbody> <tr> <td style="text-align: center;">Mold Compound</td> <td style="text-align: center;">4208625</td> <td style="text-align: center;">4222198</td> </tr> </tbody> </table> | | | | | | TI Clark | CDAT | Mold Compound | 4208625 | 4222198 |
| | TI Clark | CDAT | | | | | | | | |
| Mold Compound | 4208625 | 4222198 | | | | | | | | |
| Reason for Change: | | | | | | | | | | |
| Supply continuity | | | | | | | | | | |
| Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative): | | | | | | | | | | |
| None | | | | | | | | | | |
| Impact on Environmental Ratings | | | | | | | | | | |
| Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings. | | | | | | | | | | |
| RoHS | REACH | Green Status | IEC 62474 | | | | | | | |
| <input checked="" type="checkbox"/> No Change | <input checked="" type="checkbox"/> No Change | <input checked="" type="checkbox"/> No Change | <input checked="" type="checkbox"/> No Change | | | | | | | |
| Changes to product identification resulting from this PCN: | | | | | | | | | | |
| Assembly Site | Assembly Site Origin (22L) | Assembly Country Code (23L) | Assembly City | | | | | | | |
| TI Clark | QAB | PHL | Angeles City, Pampanga | | | | | | | |
| CDAT | CDA | CHN | Chengdu | | | | | | | |
| Sample product shipping label (not actual product label) | | | | | | | | | | |



MADE IN: Malaysia
2DC: 20:



| | |
|----------------------|----------|
| MSL '2 / 260C/1 YEAR | SEAL DT |
| MSL 1 / 235C/UNLIM | 03/29/04 |

OPT:
ITEM: 39
LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO: USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

| | | | |
|---------------|---------------|---------------|---------------|
| TPS659161RGZR | TPS659162RGZT | TPS659163RGZR | TPS659163RGZT |
| TPS659162RGZR | | | |



TI Information
Selective Disclosure

Approved 12-Aug-2021

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

| Type | Test Spec | Min Lot Qty | SS/Lot | Test Name / Condition | Duration | Qual Device: O917A130TRGZRQ1 | Pkg QBS Device: LM2775QD5GRQ1 |
|------|----------------------------------|-------------|--------|--|----------------|---------------------------------|----------------------------------|
| HAST | JEDEC JESD22-A110 | 3 | 77 | Biased HAST, 130C/85%RH | 96 hours | 1/77/0 | 3/231/0 |
| AC | JEDEC JESD22-A102 | 3 | 77 | Autoclave 121C | 96 hours | 1/77/0 | 3/231/0 |
| TC | JEDEC JESD22-A104 and Appendix 3 | 3 | 77 | Temperature Cycle, -65/150C | 500 cycles | 1/77/0 | 3/231/0 |
| HTSL | JEDEC JESD22-A103 | 1 | 45 | High Temp Storage Bake 175C | 1000 hours | 1/45/0 | 3/132/1* |
| HTOL | JEDEC JESD22-A108 | 3 | 77 | Life Test, 125C | 1000 hours | 1/77/0 | 3/231/0 |
| WBS | - | 1 | 30 | Wire Bond Shear (Cpk>1.67) | Wires | 1/30/0 | 3/90/0 |
| WBP | MIL-STD883 Method 2011 | 1 | 30 | Wire Bond Pull (Cpk>1.67) | - | - | 3/90/0 |
| SD | JEDEC JESD22-B102 | 1 | 15 | Surface Mount Solderability >95% Lead Coverage | - | - | 3/45/0 |
| PD | JEDEC JESD22-B100 and B108 | 3 | 10 | Physical Dimensions (Cpk>1.67) | Cpk>1.67 | 1/10/0 | 3/90/0 |
| CDM | - | 1 | 3 | ESD - CDM - Q100 | 1000 V | 1/3/0 | |
| Char | - | 3 | 30 | Electrical Char | Cpk>1.67 | 3/90/0 | 3/90/0 |
| MSL | - | - | - | Moist Sens. L3 | (MSL 3 / 260C) | 1/22/0 | |

- QBS: Qual By Similarity
- Qual Device O917A130TRGZRQ1 is qualified at LEVEL3-260CG

A1 (PC): Preconditioning:
Performed for THB, Biased HAST, AC, uHAST, TC & PTC samples, as applicable.

Ambient Operating Temperature by Automotive Grade Level:
Grade 0 (or E): -40°C to +150°C
Grade 1 (or Q): -40°C to +125°C
Grade 2 (or T): -40°C to +105°C
Grade 3 (or I): -40°C to +85°C

E1 (TEST): Electrical test temperatures of Qual samples:
Room/Hot/Cold: HTOL, ED
Room/Hot: THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
Room: AC/uHAST

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

| Location | E-Mail |
|-----------------|--|
| USA | PCNAmericasContact@list.ti.com |
| Europe | PCNEuropeContact@list.ti.com |
| Asia Pacific | PCNAsiaContact@list.ti.com |
| WW PCN Team | PCN_ww_admin_team@list.ti.com |

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